

TRADEMARK ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT																		
NATURE OF CONVEYANCE:	RELEASE BY SECURED PARTY																		
CONVEYING PARTY DATA																			
<table border="1" style="width: 100%;"> <tr> <th style="width: 30%;">Name</th> <th style="width: 30%;">Formerly</th> <th style="width: 20%;">Execution Date</th> <th style="width: 20%;">Entity Type</th> </tr> <tr> <td>CapitalSource Finance LLC</td> <td></td> <td>08/21/2009</td> <td>LIMITED LIABILITY COMPANY: DELAWARE</td> </tr> </table>	Name	Formerly	Execution Date	Entity Type	CapitalSource Finance LLC		08/21/2009	LIMITED LIABILITY COMPANY: DELAWARE											
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<table border="1" style="width: 100%;"> <tr> <td style="width: 20%;">Name:</td> <td>FlipChip International LLC</td> </tr> <tr> <td>Street Address:</td> <td>3701 E. University Drive</td> </tr> <tr> <td>City:</td> <td>Phoenix</td> </tr> <tr> <td>State/Country:</td> <td>ARIZONA</td> </tr> <tr> <td>Postal Code:</td> <td>85034</td> </tr> <tr> <td>Entity Type:</td> <td>LIMITED LIABILITY COMPANY: DELAWARE</td> </tr> </table>	Name:	FlipChip International LLC	Street Address:	3701 E. University Drive	City:	Phoenix	State/Country:	ARIZONA	Postal Code:	85034	Entity Type:	LIMITED LIABILITY COMPANY: DELAWARE							
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Entity Type:	LIMITED LIABILITY COMPANY: DELAWARE																		
PROPERTY NUMBERS Total: 5																			
<table border="1" style="width: 100%;"> <tr> <th style="width: 20%;">Property Type</th> <th style="width: 20%;">Number</th> <th style="width: 60%;">Word Mark</th> </tr> <tr> <td>Serial Number:</td> <td>78168486</td> <td>SPHERON</td> </tr> <tr> <td>Serial Number:</td> <td>75347767</td> <td>ULTRA CSP</td> </tr> <tr> <td>Serial Number:</td> <td>78439264</td> <td>FOC FLEX-ON-CAP</td> </tr> <tr> <td>Serial Number:</td> <td>78428935</td> <td>LIFESTYLE</td> </tr> <tr> <td>Serial Number:</td> <td>78428930</td> <td>FLIPCHIP INTERNATIONAL</td> </tr> </table>	Property Type	Number	Word Mark	Serial Number:	78168486	SPHERON	Serial Number:	75347767	ULTRA CSP	Serial Number:	78439264	FOC FLEX-ON-CAP	Serial Number:	78428935	LIFESTYLE	Serial Number:	78428930	FLIPCHIP INTERNATIONAL	
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CORRESPONDENCE DATA																			
<p>Fax Number: (602)445-8658 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Email: webbe@gtlaw.com</p> <p>Correspondent Name: Raye Lynn Daugherty</p> <p>Address Line 1: 2450 Colorado Avenue, Ste. 400E</p> <p>Address Line 4: Santa Monica, CALIFORNIA 90404</p>																			
ATTORNEY DOCKET NUMBER:	072145.015100																		

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**TRADEMARK
 REEL: 004052 FRAME: 0395**

NAME OF SUBMITTER:	Raye Lynn Daugherty
Signature:	/Raye L. Daugherty/
Date:	08/26/2009
<p>Total Attachments: 10</p> <p>source=072145015100Release#page1.tif</p> <p>source=072145015100Release#page2.tif</p> <p>source=072145015100Release#page3.tif</p> <p>source=072145015100Release#page4.tif</p> <p>source=072145015100Release#page5.tif</p> <p>source=072145015100Release#page6.tif</p> <p>source=072145015100Release#page7.tif</p> <p>source=072145015100Release#page8.tif</p> <p>source=072145015100Release#page9.tif</p> <p>source=072145015100Release#page10.tif</p>	

**RELEASE AND TERMINATION OF SECURITY INTEREST IN TRADEMARKS AND
PATENTS**

THIS RELEASE AND TERMINATION OF SECURITY INTEREST IN TRADEMARKS AND PATENTS (this "Release and Termination") is executed as of August 21, 2009, by CapitalSource Finance LLC, a Delaware limited liability company (the "Secured Party"), in favor of FlipChip International, LLC, a Delaware limited liability company (collectively, the "Pledgors").

WHEREAS, capitalized terms used and not defined herein are used with the meanings assigned to such terms in a certain Security Agreement dated as of October 13, 2005, by and between the Pledgor and the Secured Party (the "Security Agreement").

WHEREAS, the Pledgor has requested that the Secured Party release the liens and security interests granted by the Pledgor to the Secured Party in the right, title and interest of the Pledgor in, to and under the following collateral: all of the Trademarks and all of the Patents of the Pledgor, including but not limited to the Trademarks listed on Schedule I attached hereto and the Patents listed on Schedule II attached hereto, all Goodwill associated with such Trademarks and Patents, and all Proceeds of any and all of the foregoing (collectively, the "IP Collateral"), which were originally encumbered pursuant to the Security Agreement, and the Acknowledgement of Intellectual Property Collateral Lien, dated October 13, 2005, by and between the Pledgor and the Security Party (the "IP Acknowledgement"), which was recorded with the United States Patent and Trademark Office: (a) with respect to the Trademarks on (i) November 8, 2005, at Reel 3250, Frame 0088, and (ii) November 8, 2005, at Reel 3254, Frame 0290; and (b) with respect to the Patents on (i) November 1, 2005, at Reel 017186, Frame 0714, and (ii) November 8, 2005, at Reel 017207, Frame 0305.

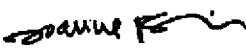
NOW THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged:

The Secured Party does hereby release and terminate the liens and security interests the Secured Party holds pursuant to the Security Agreement and the IP Acknowledgement in the Pledgor's right, title and interest in, to and under the IP Collateral, and all right, title and interest in the IP Collateral previously assigned to the Secured Party pursuant to the Security Agreement and the IP Acknowledgement are hereby reassigned to the Pledgor, without recourse or representation or warranty, express or implied, of any kind.

[The Next Page is the Signature Page]

IN WITNESS WHEREOF, the undersigned has caused this Release and Termination to be executed by its duly authorized officer as of the date first written above.

CapitalSource Finance LLC, as Agent and Lender

By: 
Name: Jeanne Fungaroli
As: Authorized Signatory

SCHEDULE I

Trademarks

(see attached)

TRADEMARKS

Serial Number	Country	Filing Date	Word Mark	Owner	Status
78/168486	US	09/27/02	Spheron	FlipChip International, LLC	Registered
75/347767	US	10/09/01	UltraCSP	FlipChip International, LLC	Registered
78/439,264	US	6/22/04	FOC Flex-On Cap	FlipChip International, LLC	Received Notices of Allowance
78/428,935	US	6/02/04	Lifestyle	FlipChip International, LLC	Received Notices of Allowance
78/428,930	US	6/02/04	FlipChip International	FlipChip International, LLC	Registered

Acknowledgement of IP Collateral Lien
CapitalSource—FlipChip
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SCHEDULE II

Patents

(see attached)

PATENTS

Intellectual Property

FlipChip Owned Intellectual Property

Patent #	Award Date	Filed	Title	Assignee
6,287,893	9/11/01	7/13/98	Method for Forming Chip Scale Package	FlipChip International, LLC
6,445,069	9/3/02	1/22/01	Electroless Ni/Pd/Au Metallization Structure for Copper Interconnect Substrate and Method Therefor	FlipChip International, LLC
6,441,487	8/27/02	10/20/97	Chip Scale Package Using Large Ductile Solder Balls	FlipChip International, LLC
6,578,755	6/17/03	9/22/00	Polymer Collar	FlipChip International, LLC
NI-171691	2/11/03	09/21/01	Polymer Collar	Flip Chip Technologies
6,750,135	06/15/04	06/20/01	Method For Forming Chip Scale Package	FlipChip International, LLC
6,919,508	06/19/05	11/10/03	Build-Up Structures with Multi-Angle Vias for Chip to Chip Interconnects and Optical Bussing	FlipChip International, LLC

Acknowledgement of IP Collateral Lien
CapitalSource—FlipChip
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TRADEMARK
REEL: 004052 FRAME: 0402

Serial Number	Country	Filing Date	Title	Assignee
09/575,298	US	5/19/00	Solder bar for High Power FlipChips	FlipChip International, LLC
2000-517447	Japan	10/19/98	Chip Scale Package Using Large Ductile Solder Balls	FlipChip Technologies, LLC
98953717.0	EPO	10/19/98	Chip Scale Package Using Large Ductile Solder Balls	FlipChip Technologies, LLC
10-2000-7004263	Korea	10/19/98	Chip Scale Package Using Large Ductile Solder Balls	FlipChip Technologies, LLC
1971260.3	EPO	9/21/01	Polymer Collar for Solder Bumps	FlipChip Technologies, LLC
10-2003-7004188	Korea	9/21/01	Polymer Collar for Solder Bumps	FlipChip Technologies, LLC
1935623.7	EPO	5/17/01	Solder bar for High Power FlipChips	FlipChip Technologies, LLC
PCT/US04/31732	International	09/27/04	Forming Partial-Depth Features In Polymer Film	FlipChip Technologies, LLC
10/672,201	US	09/26/03	Forming Partial-Depth Features In Polymer Film	FlipChip International, LLC
PCT/US04/31583	International	09/27/04	Wafer-Level Moat Structures	FlipChip Technologies, LLC
10/672,165	US	09/26/03	Wafer-Level Moat Structures	FlipChip International, LLC
60/623,200	US	10/29/04	High Performance Chip Scale Package For Radio Frequency Devices	FlipChip International, LLC
11/145,948	US	06/07/05	Build-Up Structures with Multi-Angle Vias for Chip to Chip Interconnects and Optical Bussing	FlipChip International, LLC
60/646,743	US	01/25/05	High Sensitivity Thermopile Sensor Suitable For Direct Contact Temperature Measurements	FlipChip International, LLC

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CapitalSource—FlipChip
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FlipChip Owned Inactive Filings

Serial Number	Country	Filing Date	Title	Author(s)	Description
PCT/US98/22071	International	10/18/98	Chip Scale Package Using Large Ductile Solder Balls	Peter Elenius; Harry Hollack	International versions of issued US patents
PCT/US01/15928	International	5/17/01	Solder bar for High Power FlipChips	Peter Elenius; Hong Yang	Method for forming structures for heat dissipation
PCT/US01/29509	International	09/21/01	Polymer Collar For Solder Bumps	Peter Elenius, Deok Hong Kim	
PCT/US02/01655	International	1/18/02	ElNi/Pd/Au Metallization structure for Cu Interconnect substrate and method Therfor	Jamin Ling; Dave Charles Stepniak	ElNi/Pd/Au Metallization structure for Cu Interconnect substrate and method Therfor

Licensed Intellectual Property

FlipChip holds the licenses to the patents below (the "Delphi Patents") from Delco Electronics Corporation and/or Delphi Corporation (together, "Delphi"). The licenses for the Delphi Patents were obtained under the Technology Transfer Agreement, dated as of February 28, 1996, between Delco Electronics Corporation and Flip Chip Technologies, LLC, as amended (the "Technology Transfer Agreement") and is considered "Technology" as defined therein.

Patent #	Award Date	Filed	Title	Assignee
5,547,740	8/20/96	3/23/95	Solderable Contacts for Flip Chip Integrated Circuit Devices	Delco Electronics Corp.
5,938,862	8/17/99	4/3/98	Fatigue-Resistant Lead Free Alloy	Delco Electronics Corp.
5,607,099	3/4/97	4/24/95	Solder Bump transfer device for Flip Chip Integrated Circuit Devices	Delco Electronics Corp.

Acknowledgement of IP Collateral Lien
CapitalSource—FlipChip
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Patent #	Award Date	Filed	Title	Assignee
5,632,667	5/27/97	6/29/95	No Coat Backside Wafer Grinding Process	Delco Electronics Corp.
5,803,340	9/8/98	9/29/95	Composite Solder Paste for Flip Chip Bumping	Delco Electronics Corp.
6,184,581	2/6/01	11/24/97	Solder Bump Input/Output pad for Surface mount circuit device	Delco Electronics Corp.
5,891,756	4/6/99	6/27/97	Process for Converting a Wire Bond Pad to a Flip Chip Bump Pad formed thereby	Delco Electronics Corp.
6,251,501	6/26/01	3/29/99	Surface Mount Circuit Device and Solder Bumping Method Therefor	Delco Electronics Corp.
6,281,106	8/28/01	11/25/99	Method of Solder Bumping a Circuit Component	Delco Electronics Corp.
6,375,062	4/23/02	11/6/00	Surface Bumping Method and Structure Formed Thereby	Delco Electronics Corp.
6,619,536	9/16/03	2/15/02	Solder paste composition	Delco Electronics Corp.

Acknowledgement of IP Collateral Lien
CapitalSource—FlipChip
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Patent #	Award Date	Filed	Title	Assignee
6,570,260	5/27/03	2/15/02	Solder paste composition	Delco Electronics Corp.

The patent application (the "Application") listed below is licensed from Delphi. The Application was obtained under the Technology Transfer Agreement and is considered Technology thereunder.

Serial Number	Country	Filing Date	Title
6,811,892	US	8/22/02	Lead based solder Alloys containing copper
08/511,766	US	Unknown	Method for Flip Chip Solder Bump Formulation with Solder Paste using a CFC-Free Photoresist Film

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CapitalSource—FlipChip
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